

RECOMMENDED P.C.B LAYOUT

RoHS Compliant

發行
104. 1. 09
文管中心

REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20120507	2012.05.18	Michelle
A3	Release To ECN20140212	2014.02.12	Michelle
A4	Release To ECN20150104	2015.01.09	Michelle

Specification

- 1.Current Rating:1A
- 2.Voltage Rating:50V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:100MΩ Min.
- 5.Dielectric Withstanding Voltage:AC250V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.20mm
- 3.Contact Pin:Copper Alloy T=0.20mm

Finish:

- 1.Housing:Nature
- 2.Tab:Tin Plated Over Nickel
- 3.Contact Pin:See P/N Option

Part No.: AS08601 XX K X X 1

A3 No. Of Pin
02~15,20

Packing
1:T&R
4:Tube

A4 Housing Material
K:HTN UL94V-0 Nature H.F

Plating A4
2:Matte Tin Plated Over Nickel
3:Gold Flash Over Nickel
8:Gold Plated 15u" Over Nickel

PIN	DIM.A	DIM.B	DIM.C	PIN	DIM.A	DIM.B	DIM.C	PIN	DIM.A	DIM.B	DIM.C
02	1.00	4.00	2.45	07	6.00	9.00	7.45	12	11.00	14.00	12.45
03	2.00	5.00	3.45	08	7.00	10.00	8.45	13	12.00	15.00	13.45
04	3.00	6.00	4.45	09	8.00	11.00	9.45	14	13.00	16.00	14.45
05	4.00	7.00	5.45	10	9.00	12.00	10.45	15	14.00	17.00	15.45
06	5.00	8.00	6.45	11	10.00	13.00	11.45	20	19.00	22.00	20.45

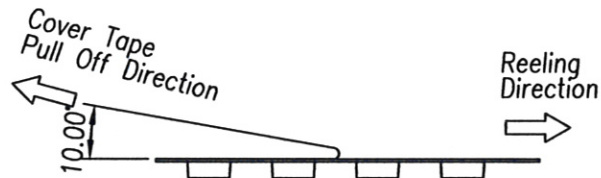
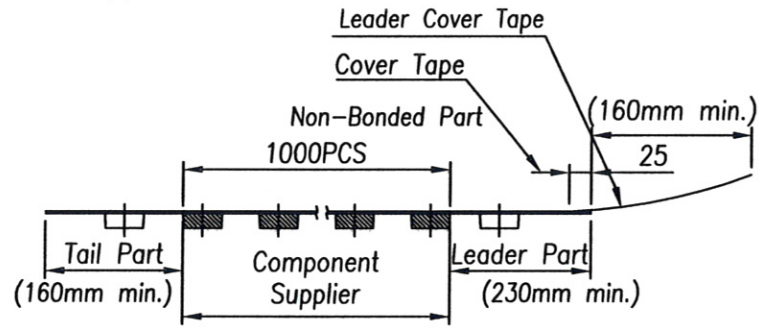
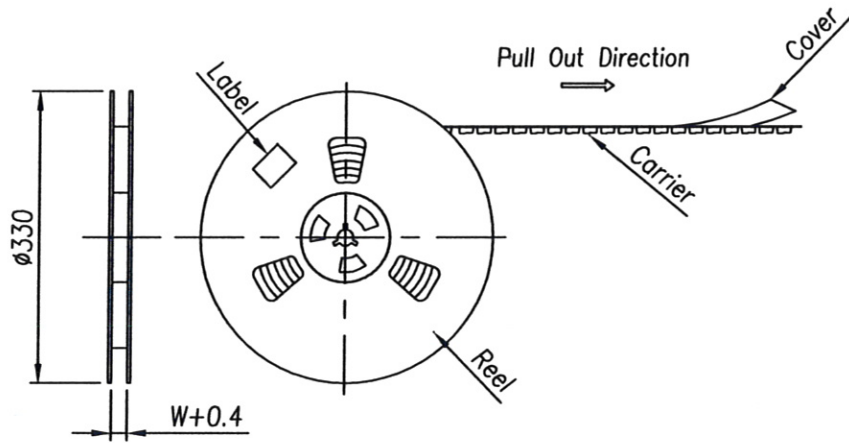


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GOLDENSUNDA TECHNOLOGY CO.,LTD

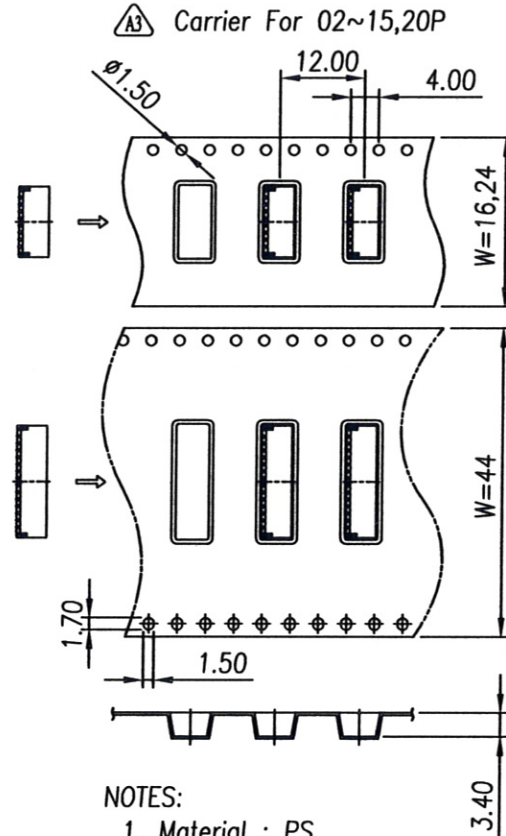
TOLERANCE UNLESS OTHERWISE SPECIFIED	PROJ.	TITLE: Wire To Board Wafer 1.00mm 90° SMT Single Row	
.x± 0.35	.x'± 2'	APR. C.F.Liao 20150109	PART NO. AS08601XXKXX1
.xx± 0.25	.x'± 1'	CHK. Abel 20150109	DWG NO. AS08601XXKXX1
.xxx± 0.15	.xx'± 0.5'	DRA. Michelle 20150109	UNITS: mm
		SIZE: A4	SCALE 6:1
		SHEET 1 / 2	REV A4
		CUSTOMER DRAWING	

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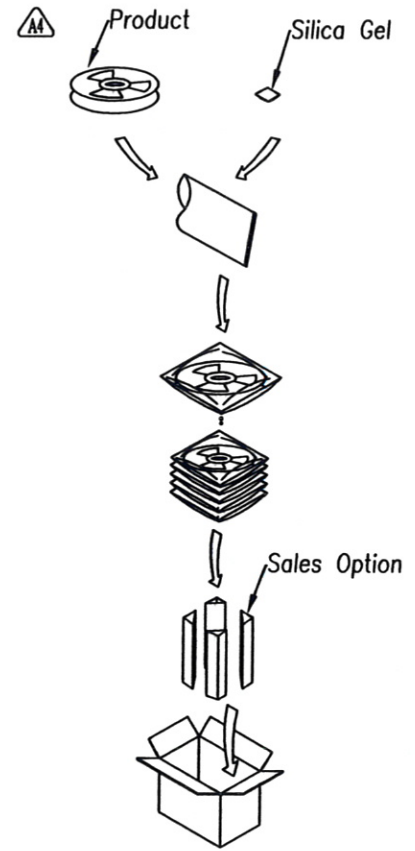
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PIN NO.	W	PCS/REEL
02 ~ 05	16	1000
06 ~ 13	24	
14~15,20	44	



- NOTES:
- Material : PS
 - Part No.: AS08601XXKX11



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.x± 0.35	x.*± 2'	APR. C.F.Liao 20150109	PART NO. AS08601XXKXX1	DWG NO. AS08601XXKXX1
.xx± 0.25	.x.*± 1'	CHK. Abel 20150109	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx.*± 0.5'	DRA. Michelle 20150109	SIZE: A4	SCALE Free
			SHEET 2 / 2	REV A4